

APPROVAL SHEET

MULTILAYER CERAMIC ANTENNA

RFANT BROADBAND Series – RoHS Compliance

2.4 GHz ISM Band Working Frequency

RFANT7635110A1T

*Contents in this sheet are subject to change without prior notice.



FEATURES

- Surface Mounted Devices with a small dimension of 7.6 x 3.5 x 1.1 mm³ meet future miniaturization trend.
- 380MHz broad bandwidth design makes less influence, less frequency shifting due to outside environmental deviation.
- 70% small footprint compared to normal band design (140MHz).
- Embedded and LTCC (Low Temperature Co-fired Ceramic) technology is able to future integrate with system design as well as beautifying the housing of final product.
- High Stability in Temperature / Humidity Change
- Free Impedance Matching

APPLICATIONS

- Bluetooth
- Wireless LAN
- HormRF
- ISM band 2.4GHz wireless applications

DESCRIPTION

Walsin Technology Corporation develops a new ceramic embedded antenna specified for 2.4 GHz ISM Band application, as shown in below "CONSTRUCTION". Both of Wireless LAN IEEE 802.11b and BluetoothTM typically located on this unlicensed frequency band which range covers from 2.4GHz to 2.4835GHz. To fulfil the friendly usage for antenna, this antenna has been designed to a typical 400MHz bandwidth through Walsin's advanced LTCC (Low Temperature Co-fired Ceramic) technology and superior product design via 3D EM Simulation Skill.

This antenna has a rectangular ceramic body with a tiny dimension of 7.6 x $3.5 \times 1.1 \text{ mm}^3$ meet the future SMT automation and miniaturization requirements on modern portable devices.

CONSTRUCTION

DIMENSIONS



Fig 1. Outline of 2.4GHz Chip Antenna



MARKING: Upon customer requested, max. 5-digit code is allowed.

SOLDER LAND PATTERN DESIGN



ELECTRICAL CHARACTERISTICS

RFANT7635110A1T	Specification
Central frequency	2.450 GHz (Note-1)
Bandwidth	380 MHz (Typical value)
Gain	0 ~ 2 dBi
VSWR	2 max.
Polarization	Linear
Azimuth Bandwidth	Omni-directional
Impedance	50Ω
Rated Power (max.)	5 Watts
Maximum Input Power	10 Watts for 5 minutes
Operation Temperature	-40° C ~ +85° C

Note-1. Central Frequency should be defined after customers' application approval.

RADIATION PATTERN

Radiation Pattern and Gain were dependent on measurement board design. Walsin's LTCC chip antenna is an electrically small antenna (size smaller than $1/10\lambda$). The specification of RFANT7635110A1x series chip antenna was measured based on the PCB size and installation position as shown in the below figure



The typical tuning range of Walsin's chip antenna is about ±150MHz. The performance of embedded ceramic antenna is sensitive influenced by customer's ground area, PC board size, thickness, material, mechanical design and the material of housing for end product.

WTC engineers have significant expertise on embedded antenna designs and applications. We can work closely with you to ensure the requirements are met, and optimise the WTC's antenna performance when installing on your application.

RELIABILITY TEST

Test item	Test condition / Test method	Specification
Solderability	*Solder bath temperature : $235 \pm 5^{\circ}$ C	At least 95% of a surface of each terminal
JIS C 0050-4.6 JESD22-B102D	*Immersion time : 2 ± 0.5 sec	electrode must be covered by fresh solder.
	*Solder : Sn3Ag0.5Cu for lead-free	
Leaching (Resistance to dissolution	*Solder bath temperature : $260 \pm 5^{\circ}C$	Loss of metallization on the edges of each
of metallization)	*Leaching immersion time : 30 ± 0.5 sec	electrode shall not exceed 25%.
IEC 60068-2-58	*Solder : SN63A	
Resistance to soldering heat		
JIS C 0050-5.4	*Preheating temperature : $120 \sim 150^{\circ}$ C,	No mechanical damage.
	1 minute.	Samples shall satisfy electrical specification
	*Solder temperature : 270±5°C	after test.
	*Immersion time : 10±1 sec	Loss of metallization on the edges of each
	*Solder : Sn3Ag0.5Cu for lead-free	electrode shall not exceed 25%.
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
Drop Test	*Height:75 cm	No mechanical damage.
JIS C 0044	*Test Surface : Rigid surface of concrete	Samples shall satisfy electrical specification
	or steel.	after test.
	*Times : 6 surfaces for each units ; 2 times for each side.	
Adhesive Strength	*Pressurizing force :	No remarkable demose or remayal of the
of Termination	$5N(\leq 0603)$; 10N(>0603)	No remarkable damage or removal of the termination.
JIS C 0051- 7.4.3	*Test time : 10±1 sec	
Bending test	The middle part of substrate shall be	No mechanical damage.
JIS C 0051- 7.4.1	pressurized by means of the pressurizing	Samples shall satisfy electrical specification
	rod at a rate of about 1 mm/s per second	after test.
	until the deflection becomes 1mm/s and	
	then pressure shall be maintained for 5 ± 1	
	sec.	
	Measurement to be made after keeping at	
	room temperature for 24±2 hours	

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Temperature cycle	1. 30±3 minutes at -40°C±3°C,	No mechanical damage.	
JIS C 0025		Samples shall satisfy electrical	
	2. 10~15 minutes at room temperature,	specification after test.	
	3. 30 ± 3 minutes at +85°C ±3 °C,		
	4. 10~15 minutes at room temperature,		
	Total 100 continuous cycles		
	Measurement to be made after keeping at		
	room temperature for 24±2 hrs		
Vibration	*Frequency : 10Hz~55Hz~10Hz(1min)	No mechanical damage.	
JIS C 0040	*Total amplitude : 1.5mm	Samples shall satisfy electrical specification	
	*Test times : 6hrs.(Two hrs each in three	after test.	
	mutually perpendicular directions)		
High temperature			
JIS C 0021	*Temperature : 85°C±2°C	No mechanical damage.	
310 0 0021	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification	
	Measurement to be made after keeping at	after test.	
	room temperature for 24±2 hrs		
Humidity	*Humidity : 90% to 95% R.H.	No mechanical damage.	
(steady conditions)	*Temperature : 40±2°C	Samples shall satisfy electrical specification	
JIS C 0022	*Time : 1000+24/-0 hrs.	after test.	
	Measurement to be made after keeping at room temperature for 24±2 hrs		
	% 500hrs measuring the first data then		
	1000hrs data		
Low temperature			
JIS C 0020	*Temperature : -40°C±2°C	No mechanical damage.	
	*Test duration : 1000+24/-0 hours	Samples shall satisfy electrical specification	
	Measurement to be made after keeping at	after test.	
	room temperature for 24±2 hrs		



SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2



Fig 2. Infrared soldering profile

ORDERING CODE

RF	ANT	763511	0	Α	1	Т
Walsin	Product code	Dimension	Unit of	Application	Specification	Packing
RF device	ANT : Antenna	code	dimension	A : 2.4GHZ ISM	Design Code	T:7" Reeled
		Per 2 digits of	0 : 0.1 mm	Band		
		Length, Width,	1 :1.0 mm	B : GSM 900/1800		
		Thickness :		Dual Band		
		e.g. :		C : GSM 900		
		763511 = Length		D : GSM 1800		
	76, Width 35, Thickness 11		E : GPS			
			F : W-CDMA			
				G : PHS		

PACKAGING: Plastic Tape specifications (unit :mm)



Index	Ao	Во	ΦD	Т	W
Dimension (mm)	3.86 ± 0.10	7.92 ± 0.10	1.55 ± 0.05	1.35 ± 0.10	16.0 ± 0.30
Index	E	F	Po	P1	P2
Dimension (mm)	1.75 ± 0.10	7.50 ± 0.10	4.00 ± 0.10	8.00 ± 0.10	2.00 ± 0.10



Reel dimensions



Index	А	В	С
Dimension (mm)	Φ178	Φ60.0	Φ13.5

Typing Quantity: 1000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.
 - Temperature : -10 to +40°C
 - Humidity : 30 to 70% relative humidity
 - Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
 - Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
 - Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
 - Products should be storage under the airtight packaged condition.